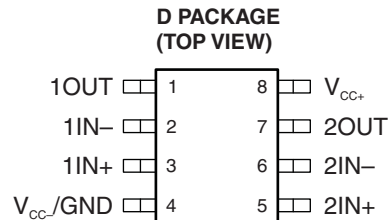


## HIGH-SLEW-RATE SINGLE-SUPPLY OPERATIONAL AMPLIFIER

### FEATURES

- Qualified for Automotive Applications
- Wide Gain-Bandwidth Product: 4 MHz
- High Slew Rate: 13 V/ $\mu$ s
- Fast Settling Time: 1.1  $\mu$ s to 0.1%
- Wide-Range Single-Supply Operation: 4 V to 36 V
- Wide Input Common-Mode Range Includes Ground ( $V_{CC-}$ )
- Low Total Harmonic Distortion: 0.02%
- Large-Capacitance Drive Capability: 10,000 pF
- Output Short-Circuit Protection



### DESCRIPTION/ORDERING INFORMATION

Quality, low-cost, bipolar fabrication with innovative design concepts is employed for the TL3472 operational amplifier. This device offers 4 MHz of gain-bandwidth product, 13-V/ $\mu$ s slew rate, and fast settling time, without the use of JFET device technology. Although the TL3472 can be operated from split supplies, it is particularly suited for single-supply operation because the common-mode input voltage range includes ground potential ( $V_{CC-}$ ). With a Darlington transistor input stage, this device exhibits high input resistance, low input offset voltage, and high gain. The all-npn output stage, characterized by no dead-band crossover distortion and large output voltage swing, provides high-capacitance drive capability, excellent phase and gain margins, low open-loop high-frequency output impedance, and symmetrical source/sink ac frequency response. This low-cost amplifier is an alternative to the MC33072 and the MC34072 operational amplifiers.

### ORDERING INFORMATION<sup>(1)</sup>

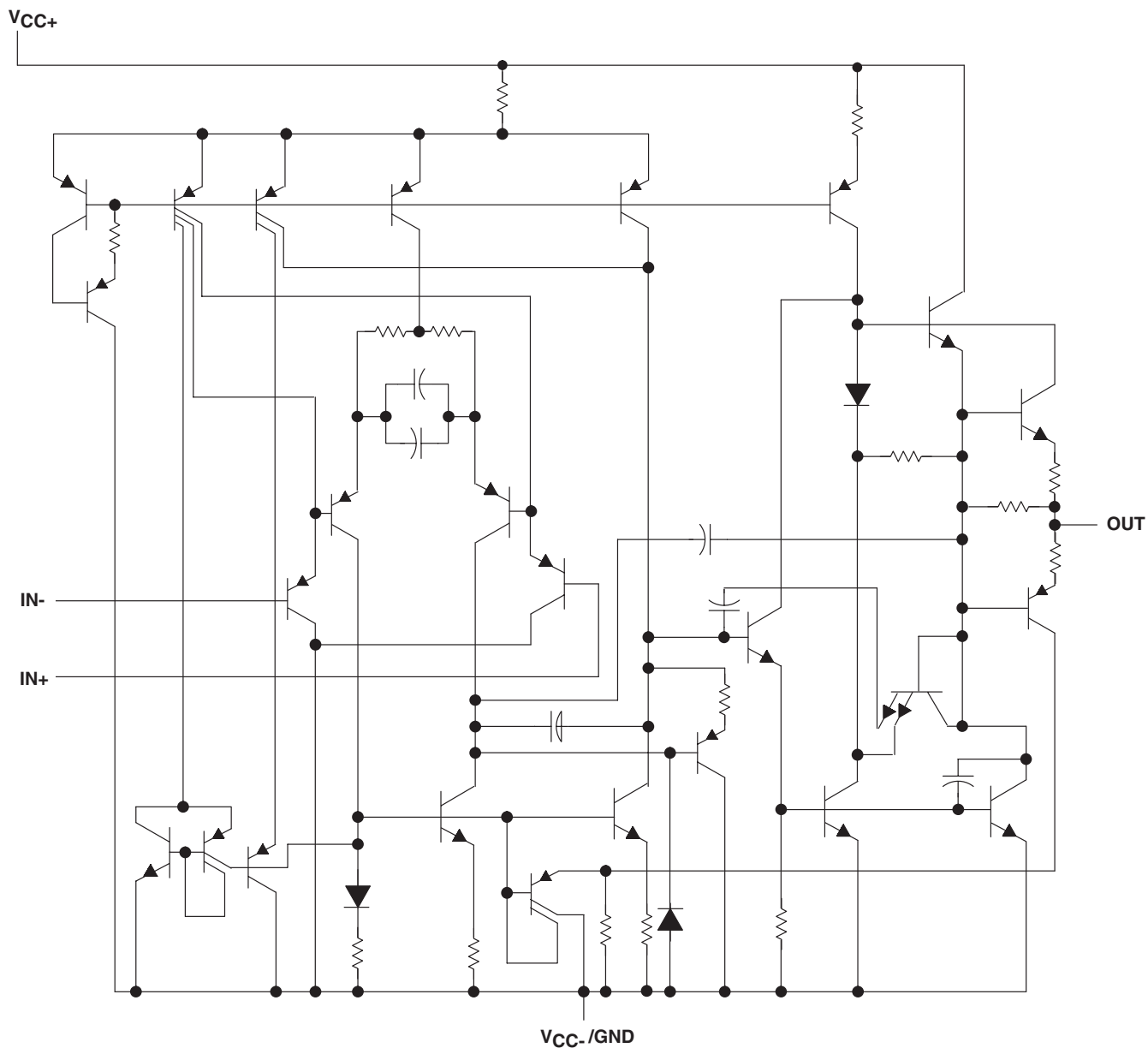
$T_A$	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC – D	Reel of 2500	TL3472QDRQ1	T3472Q

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).
- (2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).



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**SCHEMATIC (EACH AMPLIFIER)**



## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

$V_{CC+}$	Supply voltage <sup>(2)</sup>	18 V
$V_{CC-}$		–18 V
$V_{ID}$	Differential input voltage	±36 V
$V_I$	Input voltage (any input)	$V_{CC±}$
$I_I$	Input current (each input)	±1 mA
$I_O$	Output current	±80 mA
	Total current into $V_{CC+}$	80 mA
	Total current out of $V_{CC-}$	80 mA
	Duration of short-circuit current at (or below) 25°C <sup>(3)</sup>	Unlimited
$\theta_{JA}$	Package thermal impedance <sup>(4)(5)</sup>	97°C/W
$T_J$	Operating virtual junction temperature	150°C
	Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	260°C
$T_{stg}$	Storage temperature range	–65°C to 150°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to the midpoint between  $V_{CC+}$  and  $V_{CC-}$ .
- (3) The output can be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.
- (4) Maximum power dissipation is a function of  $T_J(\text{max})$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can impact reliability.
- (5) The package thermal impedance is calculated in accordance with JESD 51-7.

## RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT	
$V_{CC±}$	Supply voltage	4	36	V	
$V_{IC}$	Common-mode input voltage	$V_{CC} = 5\text{ V}$	0	2.8	V
		$V_{CC±} = ±15\text{ V}$	–15	12.8	
$T_A$	Operating free-air temperature	–40	125	°C	

### ELECTRICAL CHARACTERISTICS

at specified free-air temperature,  $V_{CC\pm} = \pm 15\text{ V}$  (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$T_A^{(1)}$	MIN	TYP <sup>(2)</sup>	MAX	UNIT	
$V_{IO}$ Input offset voltage	$V_{IC} = 0, V_O = 0, R_S = 50\ \Omega$	$V_{CC} = 5\text{ V}$	25°C	1.5	16	mV	
		$V_{CC} = \pm 15\text{ V}$	25°C	1	17		
			Full range				22
$\alpha_{VIO}$ Temperature coefficient of input offset voltage	$V_{IC} = 0, V_O = 0, R_S = 50\ \Omega$	$V_{CC} = \pm 15\text{ V}$	Full range	10		$\mu\text{V}/^\circ\text{C}$	
$I_{IO}$ Input offset current	$V_{IC} = 0, V_O = 0, R_S = 50\ \Omega$	$V_{CC} = \pm 15\text{ V}$	25°C	6	75	nA	
			Full range				300
$I_{IB}$ Input bias current	$V_{IC} = 0, V_O = 0, R_S = 50\ \Omega$	$V_{CC} = \pm 15\text{ V}$	25°C	100	500	nA	
			Full range				700
$V_{ICR}$ Common-mode input voltage range	$R_S = 50\ \Omega$		25°C	-15 to 12.8		V	
			Full range				-15 to 12.8
$V_{OH}$ High-level output voltage	$V_{CC+} = 5\text{ V}, V_{CC-} = 0, R_L = 2\text{ k}\Omega$		25°C	3.7	4	V	
			Full range	$R_L = 10\text{ k}\Omega$	13.6		14
				$R_L = 2\text{ k}\Omega$	13.4		
$V_{OL}$ Low-level output voltage	$V_{CC+} = 5\text{ V}, V_{CC-} = 0, R_L = 2\text{ k}\Omega$		25°C	0.1	0.3	V	
			Full range	$R_L = 10\text{ k}\Omega$	-14.7		-14.3
				$R_L = 2\text{ k}\Omega$	-13.5		
$A_{VD}$ Large-signal differential voltage amplification	$V_O = \pm 10\text{ V}, R_L = 2\text{ k}\Omega$		25°C	25	100	V/mV	
			Full range				20
$I_{OS}$ Short-circuit output current	Source: $V_{ID} = 1\text{ V}, V_O = 0$	25°C		-10	-34	mA	
	Sink: $V_{ID} = -1\text{ V}, V_O = 0$			20	27		
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICR}(\text{min}), R_S = 50\ \Omega$	25°C	65	97		dB	
$k_{SVR}$ Supply-voltage rejection ratio ( $\Delta V_{CC\pm}/\Delta V_{IO}$ )	$V_{CC\pm} = \pm 13.5\text{ V to } \pm 16.5\text{ V}, R_S = 100\ \Omega$	25°C	70	97		dB	
$I_{CC}$ Supply current (per channel)	$V_O = 0, \text{ No load}$		25°C	3.5	4.5	mA	
			Full range	4.5	5.5		
				25°C	3.5		4.5

(1) Full range  $T_A = -40^\circ\text{C to } 125^\circ\text{C}$

(2) All typical values are at  $T_A = 25^\circ\text{C}$ .

**OPERATING CHARACTERISTICS**
 $V_{CC\pm} = \pm 15\text{ V}$ ,  $T_A = 25^\circ\text{C}$ 

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
SR+	Positive slew rate	$V_I = -10\text{ V to } 10\text{ V}$ , $R_L = 2\text{ k}\Omega$ , $C_L = 300\text{ pF}$	$A_V = 1$	8	10		$\text{V}/\mu\text{s}$
SR–	Negative slew rate	$V_I = -10\text{ V to } 10\text{ V}$ , $R_L = 2\text{ k}\Omega$ , $C_L = 300\text{ pF}$	$A_V = -1$		13		$\text{V}/\mu\text{s}$
$t_s$	Settling time	$A_{VD} = -1$ , 10-V step	$T_O 0.1\%$		1.1		$\mu\text{s}$
			$T_O 0.01\%$		2.2		
$V_n$	Equivalent input noise voltage	$f = 1\text{ kHz}$ , $R_S = 100\ \Omega$			49		$\text{nV}/\sqrt{\text{Hz}}$
$I_n$	Equivalent input noise current	$f = 1\text{ kHz}$			0.22		$\text{pA}/\sqrt{\text{Hz}}$
THD	Total harmonic distortion	$V_{O(PP)} = 2\text{ V to } 20\text{ V}$ , $R_L = 2\text{ k}\Omega$ , $A_{VD} = 10$ , $f = 10\text{ kHz}$			0.02		%
GBW	Gain-bandwidth product	$f = 100\text{ kHz}$		3	4		MHz
BW	Power bandwidth	$V_{O(PP)} = 20\text{ V}$ , $R_L = 2\text{ k}\Omega$ , $A_{VD} = 1$ , THD = 5.0%			160		kHz
$\phi_m$	Phase margin	$R_L = 2\text{ k}\Omega$	$C_L = 0$		70		deg
			$C_L = 300\text{ pF}$		50		
	Gain margin	$R_L = 2\text{ k}\Omega$	$C_L = 0$		12		dB
			$C_L = 300\text{ pF}$		4		
$r_i$	Differential input resistance	$V_{IC} = 0$			150		$\text{M}\Omega$
$C_i$	Input capacitance	$V_{IC} = 0$			2.5		pF
	Channel separation	$f = 10\text{ kHz}$			101		dB
$z_o$	Open-loop output impedance	$f = 1\text{ MHz}$ , $A_V = 1$			20		$\Omega$

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL3472QDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL3472QDRQ1	SOIC	D	8	2500	356.0	356.0	35.0



D0008A

# PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

- Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed  $.006$  [0.15] per side.
- This dimension does not include interlead flash.
- Reference JEDEC registration MS-012, variation AA.



# EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:8X



SOLDER MASK DETAILS

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON .005 INCH [0.125 MM] THICK STENCIL  
SCALE:8X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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